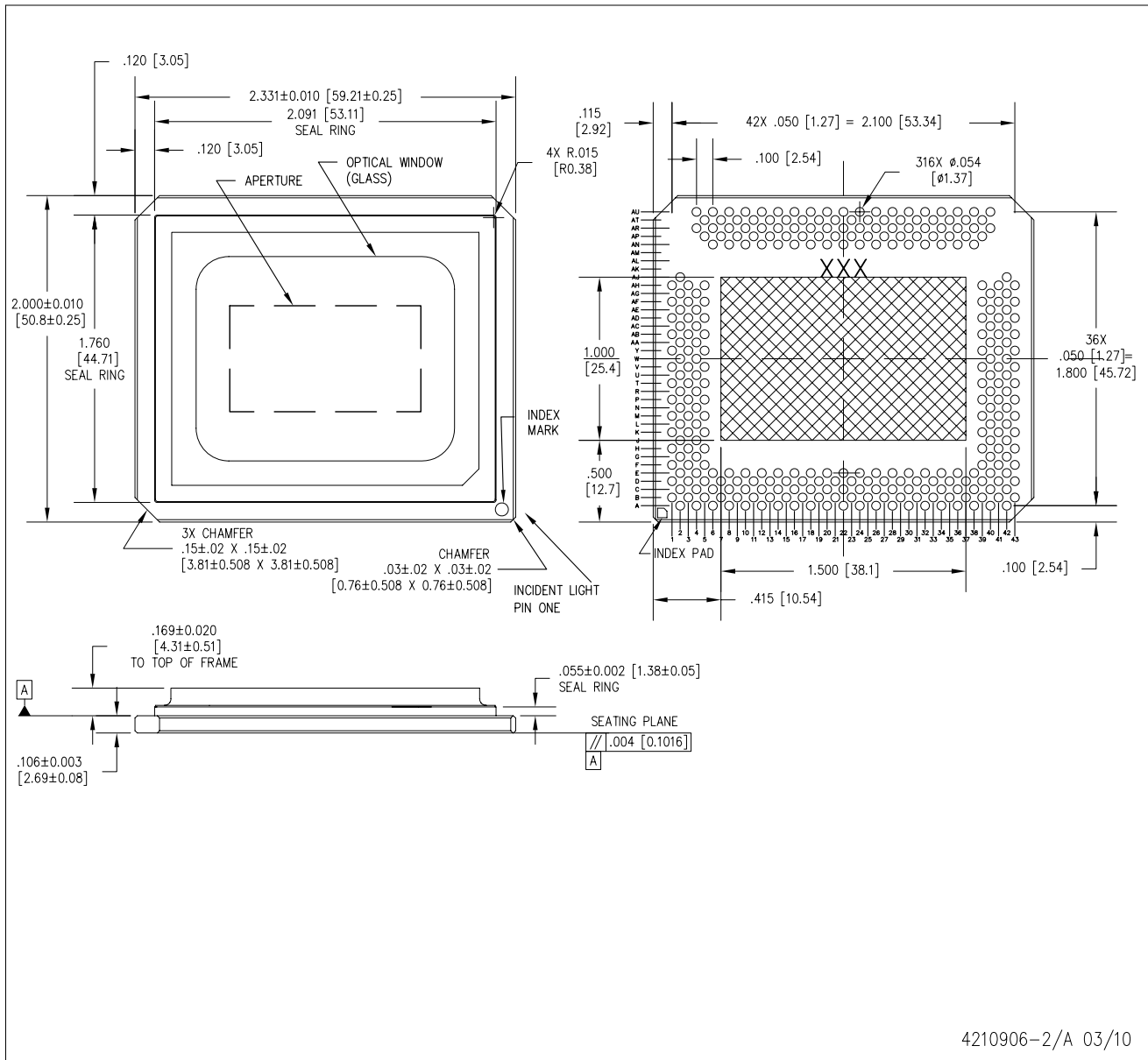


FLL (R-CLGA-N316)

CERAMIC LAND GRID ARRAY



4210906-2/A 03/10

- NOTES:
- All linear dimensions are in inches [millimeters].
 - This drawing is subject to change without notice.
 - Base material is Aluminum Oxide (Al₂O₃), seal ring and window frame Iron-Nickel-cobalt per ASTM F-15 and the optical window is Corning 7056 glass.
 - Aperture size and die active array are product specific. See respective Mechanical ICD.
 - Datum A surface is the customer optical locating and die attach surface plane.
 - Seating plane is the electrical interface surface to the customer's interposer.
 - All metal surfaces are gold plate metalization over nickel.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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